

ABSTRACT

A porous-material-forming photo-curing resin composition comprising:

5 a photo-polymerizable monomer (A) having a surface tension of not more than 25×10^{-5} N/cm,

 an organic compound (B) that is non-compatible with the photo-polymerizable monomer (A),

 a common solvent (C) that is compatible with the
10 photo-polymerizable monomer (A) and the organic compound (B); and

 a photo-polymerization initiator (D); and

 a porous resin cured product which is obtained by
photo-curing the above composition and has a very low
15 surface tension.